

LTC3129-1

15V, 200mA Synchronous Buck-Boost DC/DC Converter with 1.3µA Quiescent Current

## FEATURES DESCRIPTION

- $\blacksquare$  Regulates  $V_{\text{OUT}}$  Above, Below or Equal to  $V_{\text{IN}}$
- <sup>n</sup> **Wide VIN Range: 2.42V to 15V, 1.92V to 15V After Start-Up (Bootstrapped)**
- <sup>n</sup> **Fixed Output Voltage with Eight User-Selectable Settings from 2.5V to 15V**
- <sup>n</sup> **200mA Output Current in Buck Mode**
- Single **Inductor**
- 1.3µA Quiescent Current
- **Programmable Maximum Power Point Control**
- 1.2MHz Ultralow Noise PWM
- Current Mode Control
- Pin Selectable Burst Mode<sup>®</sup> Operation
- Up to 95% Efficiency
- Accurate RUN Pin Threshold
- **Power Good Indicator**
- 10nA Shutdown Current
- Thermally Enhanced 3mm  $\times$  3mm QFN and 16-Lead MSOP Packages

### Applications

- Industrial Wireless Sensor Nodes
- Post-Regulator for Harvested Energy
- Solar Panel Post-Regulator/Charger
- Intrinsically Safe Power Supplies
- Wireless Microphones
- Avionics-Grade Wireless Headsets

The LTC®3129-1 is a high efficiency, 200mA buck-boost DC/DC converter with a wide  $V_{IN}$  and  $V_{OUT}$  range. It includes an accurate RUN pin threshold to allow predictable regulator turn-on and a maximum power point control (MPPC) capability that ensuresmaximumpower extraction from non-ideal power sources such as photovoltaic panels.

The LTC3129-1 employs an ultralow noise, 1.2MHz PWM switching architecture that minimizes solution footprint by allowing the use of tiny, low profile inductors and ceramic capacitors. Built-in loop compensation and soft-start simplify the design. For high efficiency operation at light loads, automatic Burst Mode operation can be selected, reducing the quiescent current to just 1.3µA. To further reduce part count and improve light load efficiency, the LTC3129-1 includes an internal voltage divider to provide eight selectable fixed output voltages.

Additional features include a power good output, less than 10nA of shutdown current and thermal shutdown.

The LTC3129-1 is available in thermally enhanced  $3mm \times 3mm$  QFN and 16-lead MSOP packages. For an adjustable output voltage, see the functionally equivalent LTC3129.

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100

**EFFICIENCY** 



#### **Efficiency and Power Loss vs Load**



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1000

1

# Absolute Maximum Ratings

**(Notes 1, 8)**





# Pin Configuration



# Order Information



Consult LTC Marketing for parts specified with wider operating temperature ranges.

For more information on lead free part marking, go to: http://www.linear.com/leadfree/

For more information on tape and reel specifications, go to: http://www.linear.com/tapeandreel/. Some packages are available in 500 unit reels through designated sales channels with #TRMPBF suffix.



### Electrical Characteristics **The** <sup>l</sup> **denotes the specifications which apply over the specified operating**

**junction temperature range, otherwise specifications are at TA = 25°C (Note 2). Unless otherwise noted, VIN = 12V, VOUT = 5V.**





### Electrical Characteristics **The** l **denotes the specifications which apply over the specified operating**

**junction temperature range, otherwise specifications are at TA = 25°C (Note 2). Unless otherwise noted, VIN = 12V, VOUT = 5V.**



**Note 1:** Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime.

**Note 2:** The LTC3129-1 is tested under pulsed load conditions such that  $T_{\text{J}} \approx T_A$ . The LTC3129E-1 is guaranteed to meet specifications from 0°C to 85°C junction temperature. Specifications over the –40°C to 125°C operating junction temperature range are assured by design, characterization and correlation with statistical process controls. The LTC3129I-1 is guaranteed over the full –40°C to 125°C operating junction temperature range. The junction temperature  $(T_J, in \, ^\circ\text{C})$  is calculated from the ambient temperature ( $T_A$ , in °C) and power dissipation ( $P_D$ , in watts) according to the formula:

 $T_{\rm J} = T_{\rm A} + (P_{\rm D} \bullet \theta_{\rm J} A),$ 

where  $\theta_{JA}$  (in °C/W) is the package thermal impedance.

Note that the maximum ambient temperature consistent with these specifications is determined by specific operating conditions in conjunction with board layout, the rated thermal package thermal resistance and other environmental factors.

**Note 3:** Specification is guaranteed by design and not 100% tested in production.

**Note 4:** Current measurements are made when the output is not switching. **Note 5:** This IC includes overtemperature protection that is intended to protect the device during momentary overload conditions. Junction temperature will exceed 125°C when overtemperature protection is active. Continuous operation above the specified maximum operating junction temperature may result in device degradation or failure.

**Note 6:** Failure to solder the exposed backside of the package to the PC board ground plane will result in a much higher thermal resistance.

**Note 7:** Switch timing measurements are made in an open-loop test configuration. Timing in the application may vary somewhat from these values due to differences in the switch pin voltage during non-overlap durations when switch pin voltage is influenced by the magnitude and duration of the inductor current.

**Note 8:** Voltage transients on the switch pin(s) beyond the DC limits specified in the Absolute Maximum Ratings are non-disruptive to normal operation when using good layout practices as described elsewhere in the data sheet and Application Notes and as seen on the product demo board.

### Typical Performance Characteristics **TA = 25°C, unless otherwise noted.**



31291fc

5



## Typical Performance Characteristics **TA = 25°C, unless otherwise noted.**





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7



# Typical Performance Characteristics **TA = 25°C, unless otherwise noted.**



 $V_{OUT} = 5V$ 

1ms/DIV 31291 G29



8





### PIN FUNCTIONS (QFN/MSOP)

**BST1 (Pin 1/Pin 15):** Boot-Strapped Floating Supply for High Side NMOS Gate Drive. Connect to SW1 through a 22nF capacitor, as close to the part as possible. The value is not critical. Any value from 4.7nF to 47nF may be used.

**V<sub>IN</sub>** (Pin 2/Pin 16): Input Voltage for the Converter. Connect a minimum of 4.7µF ceramic decoupling capacitor from this pin to the ground plane, as close to the pin as possible.

**V<sub>CC</sub>** (Pin 3/Pin 1): Output Voltage of the Internal Voltage Regulator. This is the supply pin for the internal circuitry. Bypass this output with a minimum of 2.2µF ceramic capacitor close to the pin. This pin may be back-driven by an external supply, up to a maximum of 5.5V.

**RUN (Pin 4/Pin 2):** Input to the Run Comparator. Pull this pin above 1.1V to enable the  $V_{CC}$  regulator and above 1.28V to enable the converter. Connecting this pin to a resistor divider from  $V_{IN}$  to ground allows programming a  $V_{IN}$  start threshold higher than the 1.8V (typical)  $V_{IN}$  UVLO threshold. In this case, the typical  $V_{IN}$  turn-on threshold is determined by  $V_{IN} = 1.22V \cdot [1+(R3/Pin R4)]$  (see Figure 2).

**MPPC (Pin 5/Pin 3):** Maximum Power Point Control Programming Pin. Connect this pin to a resistor divider from  $V_{IN}$  to ground to enable the MPPC functionality. If the  $V_{\text{OUT}}$  load is greater than what the power source can provide, the MPPC will reduce the inductor current to regulate  $V_{IN}$  to a voltage determined by:  $V_{IN} = 1.175V$ • [1 + (R5/R6)] (see Figure 3). By setting the  $V_{IN}$  regulation voltage appropriately, maximum power transfer from the limited source is assured. Note this pin is very noise sensitive, therefore minimize trace length and stray capacitance. Please refer to the Applications Information section for more detail on programming the MPPC for different sources. If this function is not needed, tie the pin to  $V_{CC}$ .

**GND (Pin 6/Pin 4):** Signal Ground. Provide a short direct PCB path between GND and the ground plane where the exposed pad is soldered.

**VS3 (Pin 7/Pin 5):** Output Voltage Select Pin. Connect this pin to ground or  $V_{CC}$  to program the output voltage (see Table 1). This pin should not float or go below ground. If this pin is externally driven above  $V_{CC}$ , a 1M resistor should be added in series.

**VS2 (Pin 8/Pin 6):** Output Voltage Select Pin. Connect this pin to ground or  $V_{\text{CC}}$  to program the output voltage (see Table 1). This pin should not float or go below ground.

**VS1 (Pin 9/Pin 7):** Output Voltage Select Pin. Connect this pin to ground or  $V_{CC}$  to program the output voltage (see Table 1). This pin should not float or go below ground.

**PWM (Pin 10/Pin 8):** Mode Select Pin.

PWM = Low (ground): Enables automatic Burst Mode operation.

PWM = High (tie to  $V_{CC}$ ): Fixed frequency PWM operation.

This pin should not be allowed to float. It has internal 5M pull-down resistor.

**PGOOD (Pin 11/Pin 9):** Open drain output that pulls to ground when FB drops too far below its regulated voltage. Connect a pull-up resistor from this pin to a positive supply. This pin can sink up to the absolute maximum rating of 15mA when low. Refer to the Operation section of the data sheet for more detail.

**V<sub>OUT</sub>** (Pin 12/Pin 10): Output voltage of the converter, set by the VS1-VS3 programming pins according to Table 1. Connect aminimumvalue of 4.7µF ceramic capacitorfrom this pin to the ground plane, as close to the pin as possible.

**BST2 (Pin 13/Pin 11):** Boot-Strapped Floating Supply for High Side NMOS Gate Drive. Connect to SW2 through a 22nF capacitor, as close to the part as possible. The value is not critical. Any value from 4.7nF to 47nF may be used

**SW2 (Pin 14/Pin 12):** Switch Pin. Connect to one side of the inductor. Keep PCB trace lengths as short and wide as possible to reduce EMI.





## PIN FUNCTIONS (QFN/MSOP)

PGND (Pin 15/Pin 13, Exposed Pad Pin 17/Pin 17): Power Ground. Provide a short direct PCB path between PGND and the ground plane. **The exposed pad must also be soldered to the PCB ground plane**. It serves as a power ground connection, and as a means of conducting heat away from the die.

**SW1 (Pin 16/Pin 14):** Switch Pin. Connect to one side of the inductor. Keep PCB trace lengths as short and wide as possible to reduce EMI.



**Table 1. V. Dragram Cottings** 

# Block Diagram





### **Introduction**

The LTC3129-1 is a 1.3µA quiescent current, monolithic, current mode, buck-boost DC/DC converter that can operate over awide input voltage rangeof 1.92Vto 15Vandprovide up to 200mA to the load. Eight fixed, user-programmable output voltages can be selected using the three digital programming pins. Internal, low  $R_{DS(ON)}$  N-channel power switches reduce solution complexity and maximize efficiency. A proprietary switch control algorithm allows the buck-boost convertertomaintainoutput voltage regulation with input voltages that are above, below or equal to the output voltage. Transitions between the step-up or stepdown operating modes are seamless and free of transients and sub-harmonic switching, making this product ideal for noise sensitive applications. The LTC3129-1 operates at a fixed nominal switching frequency of 1.2MHz, which provides an idealtrade-off between small solution size and high efficiency. Current mode control provides inherent input line voltage rejection, simplified compensation and rapid response to load transients.

Burst Mode capability is also included in the LTC3129-1 and is user-selected via the PWM input pin. In Burst Mode operation, theLTC3129-1 provides exceptional efficiency at light output loading conditions by operating the converter only when necessary to maintain voltage regulation. The BurstMode quiescent current is amiserly 1.3µA. At higher loads, the LTC3129-1 automatically switches to fixed frequencyPWMmodewhenBurstModeoperationisselected. (Please refer to the Typical Performance Characteristic curves for the mode transition point at different input and output voltages). If the application requires extremely low noise, continuous PWM operation can also be selected via the PWM pin.

A MPPC (maximum power point control) function is also provided that allows the input voltage to the converter to be servo'd to a programmable point for maximum power when operating from various non-ideal power sources such as photovoltaic cells. The LTC3129-1 also features an accurate RUN comparator threshold with hysteresis, allowing the buck-boost DC/DC converter to turn on and off at user-selected  $V_{IN}$  voltage thresholds. With a wide

voltage range, 1.3µA Burst Mode current and programmable RUN and MPPC pins, the LTC3129-1 is well suited for many diverse applications.

### **PWM Mode Operation**

If the PWM pin is high or if the load current on the converter is high enough to command PWM mode operation with PWM low, the LTC3129-1 operates in a fixed 1.2MHz PWM mode using an internally compensated average current mode control loop. PWM mode minimizes output voltage ripple and yields a low noise switching frequency spectrum. A proprietary switching algorithm provides seamless transitions between operating modes and eliminates discontinuities in the average inductor current, inductor ripple current and loop transfer function throughout all modes of operation. These advantages result in increased efficiency, improved loop stability and lower output voltage ripple in comparison to the traditional buck-boost converter.

Figure 1 shows the topologyoftheLTC3129-1 power stage which is comprised of four N-channel DMOS switches and their associated gate drivers. In PWM mode operation both switch pins transition on every cycle independent of the input and output voltages. In response to the internal control loop command, an internal pulse width modulator generates the appropriate switch duty cycle to maintain regulation of the output voltage.



**Figure 1. Power Stage Schematic**



When stepping down from a high input voltage to a lower output voltage, the converter operates in buck mode and switch D remains on for the entire switching cycle except for the minimum switch low duration (typically 90ns). During the switch low duration, switch C is turned on which forces SW2 low and charges the flying capacitor,  $C_{\text{RST2}}$ . This ensures that the switch D gate driver power supply rail on BST2 is maintained. The duty cycle of switches A and B are adjusted to maintain output voltage regulation in buck mode.

If the input voltage is lower than the output voltage, the converter operates in boost mode. Switch A remains on for the entire switching cycle except for the minimum switch low duration (typically 90ns). During the switch low duration, switch B is turned on which forces SW1 low and charges the flying capacitor,  $C_{RST1}$ . This ensures that the switch A gate driver power supply rail on BST1 is maintained. The duty cycle of switches C and D are adjusted to maintain output voltage regulation in boost mode.

#### **Oscillator**

The LTC3129-1 operates from an internal oscillator with a nominalfixed frequency of 1.2MHz. This allows theDC/DC converter efficiency to be maximized while still using small external components.

### **Current Mode Control**

The LTC3129-1 utilizes average current mode control for the pulse width modulator. Current mode control, both average and the better known peak method, enjoy some benefits compared to other control methods including: simplified loop compensation, rapid response to load transients and inherent line voltage rejection.

Referring to the Block Diagram, a high gain, internally compensated transconductance amplifier monitors  $V_{OUT}$ throughaninternal voltagedivider. The error amplifieroutput is used by the current mode control loop to command the appropriate inductor current level. The inverting input of the internally compensated average current amplifier is connected to the inductor current sense circuit. The average current amplifier's output is compared to the oscillator ramps, and the comparator outputs are used to control the duty cycle of the switch pins on a cycle-by-cycle basis.

The voltage error amplifier monitors the output voltage,  $V_{\Omega I1T}$  through the internal voltage divider and makes adjustments to the current command as necessary to maintain regulation. The voltage error amplifier therefore controls the outer voltage regulation loop. The average current amplifier makes adjustments to the inductor current as directed by the voltage error amplifier output via  $V_C$  and is commonly referred to as the inner current loop amplifier.

The average current mode control technique is similar to peak current mode control except that the average current amplifier, by virtue of its configuration as an integrator, controls average current instead of the peak current. This difference eliminates the peak to average current error inherent to peak current mode control, while maintaining most of the advantages inherent to peak current mode control.

Average current mode control requires appropriate compensation for the inner current loop, unlike peak current mode control. The compensation network must have high DC gain to minimize errors between the actual and commanded average current level, high bandwidth to quickly change the commanded current level following transient load steps and a controlled mid-band gain to provide a form of slope compensation unique to average current mode control. The compensation components required to ensure proper operation have been carefully selected and are integrated within the LTC3129-1.

#### **Inductor Current Sense and Maximum Output Current**

As part of the current control loop required for current mode control, the LTC3129-1 includes a pair of current sensing circuits that measure the buck-boost converter inductor current.

The voltage error amplifier output,  $V_C$ , is internally clamped to a nominal level of 0.6V. Since the average inductor current is proportional to  $V_c$ , the 0.6V clamp level sets the maximum average inductor current that can be programmed by the inner current loop. Taking into account the current sense amplifier's gain, the maximum average





inductor current is approximately 275mA (typical). In buck mode, the output current is approximately equal to the inductor current  $I<sub>L</sub>$ .

```
I_{\text{OUT(BUK)}} \approx I_{\text{L}} \cdot 0.89
```
The 90ns SW1/SW2 forced low time on each switching cycle briefly disconnects the inductor from  $V_{\text{OUT}}$  and  $V_{\text{IN}}$ resulting in about 11% less output current in either buck orBoostmode for a given inductor current. In boostmode, the output current is related to average inductor current and duty cycle by:

 $I_{\text{OUT}(BOOST)} \approx I_L \bullet (1 - D) \bullet \text{Efficiency}$ 

where D is the converter duty cycle.

Since the output current in boost mode is reduced by the duty cycle (D), the output current rating in buck mode is always greater than in boost mode. Also, because boost mode operation requires a higher inductor current for a given output current compared to buck mode, the efficiency in boost mode will be lower due to higher l $_{\mathsf{L}}{}^2\bullet\mathsf{R}_{\mathsf{DS}(\mathsf{ON})}$ losses in the power switches. This will further reduce the output current capability inboostmode. Ineitheroperating mode, however, the inductor peak-to-peak ripple current does not play a major role in determining the output current capability, unlike peak current mode control.

With peak current mode control, the maximum output current capability is reduced by the magnitude of inductor ripple current because the peak inductor current level is the control variable, but the average inductor current is what determines the output current. The LTC3129-1 measures and controls average inductor current, and therefore, the inductor ripple current magnitude has little effect on the maximum current capability in contrast to an equivalent peak current mode converter. Under most conditions in buck mode, the LTC3129-1 is capable of providing a minimum of 200mA to the load. In boost mode, as described previously, the output current capability is related to the boost ratio or duty cycle (D). For example, for a 3.6V  $V_{\text{IN}}$ to 5V output application, the LTC3129-1 can provide up to 150mA to the load. Refer to the Typical Performance Characteristics section for more detail on output current capability.

### **Overload Current Limit and I<sub>ZERO</sub> Comparator**

The internal current sense waveform is also used by the peak overload current ( $I_{PEAK}$ ) and zero current ( $I_{ZERO}$ ) comparators. The  $I_{PFAK}$  current comparator monitors  $I_{SFRSF}$ and turns off switch A if the inductor current level exceeds its maximum internal threshold, which is approximately 500mA. An inductor current level of this magnitude will occur during a fault, such as an output short-circuit, or during large load or input voltage transients.

The LTC3129-1 features near discontinuous inductor current operation at light output loads by virtue of the  $I_{\rm ZFRO}$  comparator circuit. By limiting the reverse current magnitude in PWM mode, a balance between low noise operationandimprovedefficiency atlightloads isachieved. The  $I_{\rm ZERO}$  comparator threshold is set near the zero current level in PWM mode, and as a result, the reverse current magnitude will be a function of inductance value and output voltage due to the comparator's propagation delay. In general, higher output voltages and lower inductor values will result in increased reverse current magnitude.

In automatic Burst Mode operation (PWM pin low), the  $I_{\rm ZFRO}$  comparator threshold is increased so that reverse inductor current does not normally occur. This maximizes efficiency at very light loads.

### **Burst Mode Operation**

When the PWM pin is held low, the LTC3129-1 is configured for automatic Burst Mode operation. As a result, the buck-boost DC/DC converter will operate with normal continuous PWM switching above a predetermined minimumoutputloadandwill automatically transitiontopower saving Burst Mode operation below this output load level. Note that if the PWM pin is low, reverse inductor current is not allowed at any load. Refer to the Typical Performance Characteristics section of this data sheet to determine the Burst Mode transition threshold for various combinations of  $V_{IN}$  and  $V_{OIII}$ . If PWM is low, at light output loads, the



LTC3129-1 will go into a standby or sleep state when the output voltage achieves its nominal regulation level. The sleep state halts PWM switching and powers down all nonessential functions of the IC, significantly reducing the quiescent current of the LTC3129-1 to just 1.3µA typical. This greatly improves overall power conversion efficiency when the output load is light. Since the converter is not operating in sleep, the output voltage will slowly decay at a rate determined by the output load resistance and the output capacitor value. When the output voltage has decayed by a small amount, the LTC3129-1 will wake and resume normal PWM switching operation until the voltage on  $V_{\text{OUT}}$  is restored to the previous level. If the load is very light, the LTC3129-1 may only need to switch for a few cycles to restore  $V_{\text{OUT}}$  and may sleep for extended periods of time, significantly improving efficiency. If the load is suddenly increased above the burst transition threshold, the part will automatically resume continuous PWM operation until the load is once again reduced.

Note that Burst Mode operation is inhibited until soft-start is done, the MPPC pin is greater than 1.175V and  $V_{\text{OUT}}$ has reached regulation.

### **Soft-Start**

The LTC3129-1 soft-start circuit minimizes input current transients and output voltage overshoot on initial power up. The required timing components for soft-start are internal to the LTC3129-1 and produce a nominal soft-start duration of approximately 3ms. The internal soft-start circuit slowly ramps the error amplifier output,  $V_C$ . In doing so, the current command of the IC is also slowly increased, starting from zero. It is unaffected by output loading or output capacitor value. Soft-start is reset by the UVLO on both  $V_{IN}$  and  $V_{CC}$ , the RUN pin and thermal shutdown.

### **V<sub>CC</sub>** Regulator

An internal lowdropoutregulator (LDO) generates a nominal 4.1V V<sub>CC</sub> rail from V<sub>IN</sub>. The V<sub>CC</sub> rail powers the internal control circuitry and the gate drivers of the LTC3129-1. The  $V_{CC}$  regulator is disabled in shutdown to reduce quiescent current and is enabled by raising the RUN pin above its logic threshold. The  $V_{CC}$  regulator includes current-limit protection to safeguard against accidental short-circuiting of the  $V_{CC}$  rail.

### **Undervoltage Lockout (UVLO)**

There are two undervoltage lockout (UVLO) circuitswithin the LTC3129-1 that inhibit switching; one that monitors  $V_{IN}$ and another that monitors  $V_{CC}$ . Either UVLO will disable operation of the internal power switches and keep other IC functions in a reset state if either  $V_{IN}$  or  $V_{CC}$  are below their respective UVLO thresholds.

The  $V_{IN}$  UVLO comparator has a falling voltage threshold of 1.8V (typical). If  $V_{IN}$  falls below this level, IC operation is disabled until  $V_{IN}$  rises above 1.9V (typical), as long as the  $V_{CC}$  voltage is above its UVLO threshold.

The  $V_{CC}$  UVLO has a falling voltage threshold of 2.19V (typical). If the  $V_{CC}$  voltage falls below this threshold, IC operation is disabled until  $V_{CC}$  rises above 2.25V (typical) as long as  $V_{IN}$  is above its nominal UVLO threshold level.

Depending on the particular application, either of these UVLO thresholds could be the limiting factor affecting the minimuminput voltage requiredforoperation. Because the  $V_{CC}$  regulator uses  $V_{IN}$  for its power input, the minimum input voltage required for operation is determined by the  $V_{CC}$  minimum voltage, as input voltage ( $V_{IN}$ ) will always be higher than  $V_{CC}$  in the normal (non-bootstrapped) configuration. Therefore, the minimum  $V_{IN}$  for the part to start up is 2.25V (typical).

In applications where  $V_{CC}$  is bootstrapped (powered through a Schottky diode by either  $V_{\text{OUT}}$  or an auxiliary power rail), the minimum input voltage for operation will be limited only by the  $V_{IN}$  UVLO threshold (1.8V typical). *Please note that if the bootstrap voltage is derived from the* LTC3129-1  $V_{OUT}$  and not an independent power rail, *thentheminimuminput voltage requiredforinitial start-up is still 2.25V (typical)*.

Note that if either  $V_{IN}$  or  $V_{CC}$  are below their UVLO thresholds, or if RUN is below its accurate threshold of 1.22V (typical), then the LTC3129-1 will remain in a soft shutdown state, where the  $V_{IN}$  quiescent current will be only 1.9µA typical.



#### **VOUT** Undervoltage

There is also an undervoltage comparator that monitors the output voltage. Until  $V_{OUT}$  reaches 1.15V (typical), the average current limit is reduced by a factor of two. This reduces power dissipation in the device in the event of a shorted output. In addition, N-channel switch D, which feeds  $V_{\text{OUT}}$ , will be disabled until  $V_{\text{OUT}}$  exceeds 1.15V.

#### **RUN Pin Comparator**

In addition to serving as a logic level input to enable certain functions of the IC, the RUN pin includes an accurate internal comparator that allows it to be used to set custom rising and falling ON/OFF thresholds with the addition of an optional external resistor divider. When RUN is driven above its logic threshold (0.9V typical), the  $V_{CC}$  regulator is enabled, which provides power to the internal control circuitry of the IC. If the voltage on RUN is increased further so that it exceeds the RUN comparator's accurate analog threshold (1.22V typical), all functions of the buckboost converter will be enabled and a start-up sequence will ensue (assuming the  $V_{IN}$  and  $V_{CC}$  UVLO thresholds are satisfied).

If RUN is brought below the accurate comparator threshold, the buck-boost converter will inhibit switching, but the  $V_{CC}$ regulator and control circuitry will remain powered unless RUN is brought below its logic threshold. Therefore, in order to completely shut down the IC and reduce the  $V_{\text{IN}}$ current to 10nA (typical), it is necessary to ensure that RUNis brought belowitsworst case lowlogic threshold of 0.5V. RUN is a high voltage input and can be tied directly to  $V_{IN}$  to continuously enable the IC when the input supply is present. Also note that RUN can be driven above  $V_{\text{IN}}$ or  $V_{\text{OUT}}$  as long as it stays within the operating range of the IC (up to 15V).

With the addition of an optional resistor divider as shown in Figure 2, the RUN pin can be used to establish a userprogrammable turn-onandturn-offthreshold. This feature can be utilized to minimize battery drain below a certain input voltage, or to operate the converter in a hiccup mode from very low current sources.



**Figure 2. Accurate RUN Pin Comparator**

Note that once RUN is above 0.9V typical, the quiescent input current on  $V_{IN}$  (or  $V_{CC}$  if back-driven) will increase to about 1.9µA typical until the  $V_{IN}$  and  $V_{CC}$  UVLO thresholds are satisfied.

The converter is enabled when the voltage on RUN exceeds 1.22V (nominal). Therefore, the turn on voltage threshold on  $V_{IN}$  is given by:

 $V_{IN(TURN-ON)} = 1.22V \cdot (1 + R3/R4)$ 

The RUN comparator includes a built-in hysteresis of approximately 80mV, so that the turn off threshold will be 1.14V.

There may be cases due to PCB layout, very large value resistors for R3 and R4, or proximity to noisy components where noise pickup may cause the turn-on or turn-off of the IC to be intermittent. In these cases, a small filter capacitor can be added across R4 to ensure proper operation.

#### **PGOOD Comparator**

The LTC3129-1 provides an open-drain PGOOD output that pulls low if  $V_{\text{OUT}}$  falls more than 7.5% (typical) below its programmed value. When  $V_{\text{OUT}}$  rises to within 5% (typical) of its programmed value, the internal PGOOD pull-down will turn off and PGOOD will go high if an external pullup resistor has been provided. An internal filter prevents nuisance trips of PGOOD due to short transients on  $V_{OIII}$ . Note that PGOOD can be pulled up to any voltage, as long as the absolute maximum rating of 18V is not exceeded, and as long as the maximum sink current rating is not exceeded when PGOOD is low. Note that PGOOD will also be driven low if  $V_{CC}$  is below its UVLO threshold or



if the part is in shutdown (RUN below its logic threshold) while  $V_{CC}$  is being held up (or back-driven). PGOOD is not affected by  $V_{IN}$  UVLO or the accurate RUN threshold.

In cases where  $V_{CC}$  is not being back-driven in shutdown, PGOOD will not be held low indefinitely. The internal PGOOD pull-down will be disabled as the  $V_{CC}$  voltage decays below approximately 1V.

#### **Maximum Power-Point Control (MPPC)**

The MPPC input of the LTC3129-1 can be used with an optional external voltage divider to dynamically adjust the commanded inductor current in order to maintain a minimum input voltage when using high resistance sources, such as photovoltaic panels, so as to maximize input power transfer and prevent  $V_{IN}$  from dropping too low under load. Referring to Figure 3, the MPPC pin is internally connected to the noninverting input of a  $q_m$ amplifier, whose inverting input is connected to the 1.175V reference. If the voltage at MPPC, using the external voltage divider, falls belowthe reference voltage, the output of the amplifier pulls the internal  $V_C$  node low. This reduces the commanded average inductor current so as to reduce the input current and regulate  $V_{\text{IN}}$  to the programmed minimum voltage, as given by:

$$
\begin{array}{ccc}\nV_{IN} & & & \\
S_{RS} & \stackrel{\text{def}}{=} & C_{IN} \\
\hline\n\end{array}\n\qquad\n\begin{array}{ccc}\nR5 & & & & \\
S_{RS} & & & & \\
MPPCC & & & & \\
\hline\n\end{array}\n\qquad\n\begin{array}{ccc}\nV_{IN} & & & \text{LTC3} \\
\hline\n\end{array}
$$

 $V_{IN(MPPC)} = 1.175V \cdot (1 + R5/R6)$ 

**Figure 3. MPPC Amplifier with External Resistor Divider**

VOLTAGE ERROR AMP

–

The MPPC feature provides capabilities to the LTC3129-1 that can ease the design of intrinsically safe power supplies. For an example of an application that must operate from a supply with intentional series resistance, refer to the application example on the bottom of page 25.

Note that external compensation should not be required for MPPC loop stability if the input filter capacitor,  $C_{IN}$ , is at least 22µF. See Typical Applications for an example of external compensation that can be added in applications where  $C_{1N}$  must be less than the recommended minimum value.

The divider resistor values can be in the megohm range to minimize the input current in very low power applications. However, stray capacitance and noise pickup on theMPPC pin must also be minimized.

The MPPC pin controls the converter in a linear fashion when using sources that can provide a minimum of 5mA to 10mA of continuous input current. For operation from weakerinput sources, referto the Application Information section to see how the programmable RUN pin can be used to control the converter in a hysteretic manner to provide an effective MPPC function for sources that can provide as little as 5µA or less.

If the MPPC function is not required, the MPPC pin should be tied to  $V_{CC}$ .

### **VOUT Programming Pins**

The LTC3129-1 has a precision internal voltage divider on  $V_{\text{OUT}}$ , eliminating the need for high-value external feedback resistors. This not only eliminates two external components, it minimizes no-load quiescent current by using very



31291fc

129-1

V<sub>C</sub><br>CURRENT COMMAND

31291 FM

C<sub>IN</sub> SHOULD BE AT  $\pm$  LEAST 22µF FOR MPPC APPLICATIONS

high resistance values that would not be practical due to the effects of noise and board leakages that would cause  $V_{\text{OUT}}$ regulation errors. The tap point on this divider is digitally selected by using the VS1, VS2 and VS3 pins to program one of eight fixed output voltages. The VS pins should be grounded or connected to  $V_{CC}$  to select the desired output voltage, according to the following table. The VS1, VS2 and VS3 pins can also be driven by external logic signals as long as the absolute maximum voltage ratings are not exceeded. Note however that driving any of the voltage select pins high to a voltage less than the  $V_{CC}$  operating voltage will result in increased quiescent current. Also note that if the VS3 pin is driven above  $V_{CC}$ , an external 1M resistor should be added in series. For other output voltages, refer to the LTC3129 which has a feedback pin, allowing any output voltage from 1.4V to 15.75V.



**VOUT Program Settings for the LTC3129-1**

Note that in shutdown, or if  $V_{CC}$  is below its UVLO threshold, the internal voltage divider on  $V_{OUT}$  is automatically disconnected to eliminate any current draw on  $V_{OIII}$ .

#### **Thermal Considerations**

The power switches of the LTC3129-1 are designed to operate continuously with currents up to the internal current limit thresholds. However, when operating at high current levels, there may be significant heat generated within the IC. In addition, the  $V_{CC}$  regulator can also generate wasted heat when  $V_{IN}$  is very high, adding to the total power

dissipation of the IC. As described elsewhere in this data sheet, bootstrapping of the  $V_{CC}$  for 5V output applications can essentially eliminate the  $V_{CC}$  power dissipation term and significantly improve efficiency. As a result, careful consideration must be given to the thermal environment of the IC in order to provide a means to remove heat from the IC and ensure that the LTC3129-1 is able to provide its full rated output current. Specifically, the exposed die attach pad of both the QFN and MSE packages must be soldered to a copper layer on the PCB to maximize the conduction of heat out of the IC package. This can be accomplished by utilizing multiple vias from the die attach pad connection underneath the IC package to other PCB layer(s) containing a large copper plane. A typical board layout incorporating these concepts is shown in Figure 4.

If the IC die temperature exceeds approximately 180°C, overtemperature shutdown will be invoked and all switching will be inhibited. The part will remain disabled until the die temperature cools by approximately 10°C. The soft-start circuit is re-initialized in over temperature shutdown to provide a smooth recovery when the IC die temperature cools enough to resume operation.



**Figure 4. Typical 2-Layer PC Board Layout (MSE Package)**



A standard application circuit for the LTC3129-1 is shown on the front page of this data sheet. The appropriate selectionofexternalcomponents isdependentupontherequired performance of the IC in each particular application given considerations and trade-offs such as PCB area, input and output voltage range, output voltage ripple, transient response, required efficiency, thermal considerations and cost. This section of the data sheet provides some basic guidelines and considerations to aid in the selection of external components and the design of the applications circuit, as well as more application circuit examples.

### **V<sub>CC</sub>** Capacitor Selection

The  $V_{CC}$  output of the LTC3129-1 is generated from  $V_{IN}$ by a low dropout linear regulator. The  $V_{CC}$  regulator has been designed for stable operation with a wide range of output capacitors. For most applications, a low ESR capacitor of at least 2.2µF should be used. The capacitor should be located as close to the  $V_{CC}$  pin as possible and connected to the  $V_{CC}$  pin and ground through the shortest traces possible.  $V_{CC}$  is the regulator output and is also the internal supply pin for the LTC3129-1 control circuitry as well as the gate drivers and boost rail charging diodes. The  $V_{CC}$  pin is not intended to supply current to other external circuitry.

### **Inductor Selection**

The choice of inductor used in LTC3129-1 application circuits influences the maximum deliverable output current, the converter bandwidth, the magnitude of the inductor current ripple and the overall converter efficiency. The inductor must have a low DC series resistance, when compared to the internal switch resistance, or output current capability and efficiency will be compromised. Larger inductor values reduce inductor current ripple but may not increase output current capability as is the case with peak current mode control as described in the Maximum Output Current section. Larger value inductors also tend to have a higher DC series resistance for a given case size, which will have a negative impact on efficiency. Larger values of inductance will also lower the right half plane (RHP) zero frequency when operating in boost mode, which can compromise loop stability. Nearly all LTC3129-1 application circuits deliver the best performance with an inductor value between 3.3µH and 10µH. Buck mode

only applications can use the larger inductor values as they are unaffected by the RHP zero, while mostly boost applications generally require inductance on the low end of this range depending on how large the step-up ratio is.

Regardless of inductor value, the saturation current rating should be selected such that it is greater than the worst case average inductor current plus half of the ripple current. The peak-to-peak inductor current ripple for each operational mode can be calculated from the following formula, where f is the switching frequency (1.2MHz), L is the inductance in  $\mu$ H and  $t_{LOW}$  is the switch pin minimum low time in µs. The switch pin minimum low time is typically 0.09µs.

$$
\Delta I_{L(P-P)(BUGK)} = \frac{V_{OUT}}{L} \left( \frac{V_{IN} - V_{OUT}}{V_{IN}} \right) \left( \frac{1}{f} - t_{LOW} \right) A
$$

$$
\Delta I_{L(P-P)(BOOST)} = \frac{V_{IN}}{L} \left( \frac{V_{OUT} - V_{IN}}{V_{OUT}} \right) \left( \frac{1}{f} - t_{LOW} \right) A
$$

It should be noted that the worst-case peak-to-peak inductor ripple current occurs when the duty cycle in buck mode is minimum (highest  $V_{IN}$ ) and in boost mode when the duty cycle is 50% ( $V_{OUT} = 2 \cdot V_{IN}$ ). As an example, if  $V_{IN}$  (minimum) = 2.5V and  $V_{IN}$  (maximum) = 15V,  $V_{OUIT}$  $= 5V$  and L = 10 $\mu$ H, the peak-to-peak inductor ripples at the voltage extremes (15V  $V_{IN}$  for buck and 2.5V  $V_{IN}$  for boost) are:

BUCK = 248mA peak-to-peak

BOOST = 93mA peak-to-peak

One half of this inductor ripple current must be added to the highest expected average inductor current in order to select the proper saturation current rating for the inductor.

To avoid the possibility of inductor saturation during load transients, an inductor with a saturation current rating of at least 600mA is recommended for all applications.

31291fc In addition to its influence on power conversion efficiency, the inductor DC resistance can also impact the maximum output current capability of the buck-boost converter particularly at low input voltages. In buck mode, the output current of the buck-boost converter is primarily limited by the inductor current reaching the average current limit threshold. However, in boost mode, especially



at large step-up ratios, the output current capability can also be limited by the total resistive losses in the power stage. These losses include, switch resistances, inductor DC resistance and PCB trace resistance. Avoid inductors with a high DC resistance (DCR) as they can degrade the maximum output current capability from what is shown in the Typical Performance Characteristics section and from the Typical Application circuits.

As a guideline, the inductor DCR should be significantly less than the typical power switch resistance of  $750 \text{m}\Omega$ each. The only exceptions are applications that have a maximum output current requirement much less than what the LTC3129-1 is capable of delivering. Generally speaking, inductors with a DCR in the range of 0.15 $\Omega$  to  $0.3\Omega$  are recommended. Lower values of DCR will improve the efficiency at the expense of size, while higher DCR values will reduce efficiency (typically by a few percent) while allowing the use of a physically smaller inductor.

Differentinductor corematerials andstyleshave animpact on the size and price of an inductor at any given current rating. Shielded construction is generally preferred as it minimizes the chances of interferencewith other circuitry. The choice of inductor style depends upon the price, sizing, and EMI requirements of a particular application. Table 2 provides a wide sampling of inductors that are well suited to many LTC3129-1 applications.



#### **Table 2. Recommended Inductors**

Recommended inductor values for different operating voltage ranges are given in Table 3. These values were chosen to minimize inductor size while maintaining an acceptable amount of inductor ripple current for a given  $V_{IN}$  and  $V_{OUIT}$  range.





Due to the fixed, internal loop compensation and feedback divider provided by the LTC3129-1, there are limitations to the maximum recommended total output capacitor value in applications that must operate in PWM mode at light load (PWM pin pulled high with minimum load currents less than ~15mA). In these applications, a maximum output capacitor value, shown in Table 3, is recommended. For applications that must operate in PWM mode at light load with higher values of output capacitance, the LTC3129 is recommended. Its external feedback pin allows the use of additional feedforward compensation for improved light-load stability under these conditions.

*Note that for applications where Burst Mode operation is enabled (PWM pin grounded), the output capacitor value can be increased without limitation regardless of the minimum load current or inductor value.*

#### **Output Capacitor Selection**

A low effective series resistance (ESR) output capacitor of 4.7µF minimum should be connected at the output of the buck-boost converter in order to minimize output voltage ripple. Multilayer ceramic capacitors are an excellent option as they have low ESR and are available in small footprints. The capacitor value should be chosen large enough to reduce the output voltage ripple to acceptable levels. Neglecting the capacitor's ESR and ESL (effective series inductance), the peak-to-peak output voltage ripple in PWM mode can be calculated by the following



formula, where f is the frequency in MHz (1.2MHz),  $C_{OUT}$ is the capacitance in  $\mu$ F,  $t_{\text{LOW}}$  is the switch pin minimum low time in  $\mu$ s (0.09 $\mu$ s typical) and  $I_{\text{LOAD}}$  is the output current in amperes.

$$
\Delta V_{P-P(BUCK)} = \frac{I_{LOAD}t_{LOW}}{C_{OUT}} V
$$

$$
\Delta V_{P-P(BOOST)} = \frac{I_{LOAD}}{fC_{OUT}} \left(\frac{V_{OUT} - V_{IN} + t_{LOW}tV_{IN}}{V_{OUT}}\right) V
$$

Examining the previous equations reveals that the output voltage ripple increases with load current and is generally higher in boost mode than in buck mode. Note that these equations only take into account the voltage ripple that occurs from the inductor current to the output being discontinuous. They provide a good approximation to the ripple at any significantload current but underestimate the output voltage ripple at very light loads where the output voltage ripple is dominated by the inductor current ripple.

In addition to the output voltage ripple generated across the output capacitance, there is also output voltage ripple produced across the internal resistance of the output capacitor. The ESR-generated output voltage ripple is proportional to the series resistance of the output capacitor and is given by the following expressions where  $R_{ESR}$  is the series resistance of the output capacitor and all other terms as previously defined.

$$
\Delta V_{P-P(BUCK)} = \frac{I_{LOAD}R_{ESR}}{1 - t_{LOW}f} \approx I_{LOAD}R_{ESR} V
$$

$$
\Delta V_{P-P(BOOST)} = \frac{I_{LOAD}R_{ESR}V_{OUT}}{V_{IN}(1 - t_{LOW}f)}
$$

$$
\approx I_{LOAD}R_{ESR}\left(\frac{V_{OUT}}{V_{IN}}\right)V
$$

In most LTC3129-1 applications, an output capacitor between 10µF and 22µF will work well. To minimize output ripple in Burst Mode operation, values of 22µF operation or larger are recommended.

#### **Input Capacitor Selection**

The  $V_{IN}$  pin carries the full inductor current and provides power to internal control circuits in the IC. To minimize input voltage ripple and ensure proper operation of the IC, a low ESR bypass capacitor with a value of at least 4.7µF should be located as close to the  $V_{IN}$  pin as possible. The traces connecting this capacitor to  $V_{IN}$  and the ground plane should be made as short as possible.

When powered through long leads or from a power source with significant resistance, a larger value bulk input capacitor may be required and is generally recommended. In such applications, a 47µF to 100µF low-ESRelectrolytic capacitorin parallelwith a 1µF ceramic capacitor generally yields a high performance, low cost solution.

Note that applications using the MPPC feature should use a minimum  $C_{IN}$  of 22 $\mu$ F. Larger values can be used without limitation.

### **Recommended Input and Output Capacitor Types**

The capacitors used to filter the input and output of the LTC3129-1 must have low ESR and must be rated to handle the AC currents generated by the switching converter. This is important to maintain proper functioning of the IC and to reduce output voltage ripple. There are many capacitor types that are well suited to these applications including multilayer ceramic, low ESR tantalum, OS-CON and POSCAP technologies. In addition, there are certain types of electrolytic capacitors such as solid aluminum organic polymer capacitors that are designed for low ESR and high AC currents and these are also well suited to some LTC3129-1 applications. The choice of capacitor technology is primarily dictated by a trade-off between size, leakage current and cost. In backup power applications, the input or output capacitor might be a super or ultra capacitor with a capacitance value measuring in the farad range. The selection criteria in these applications are generally similar except that voltage ripple is generally not a concern. Some capacitors exhibit a high DC leakage current which may preclude their consideration for applications that require a very low quiescent current in Burst Mode operation. Note that ultra capacitors may have



a rather high ESR, therefore a 4.7µF (minimum) ceramic capacitor is recommended in parallel, close to the IC pins.

Ceramic capacitors are often utilized in switching converter applications due to their small size, low ESR and low leakage currents. However, many ceramic capacitors intended for power applications experience a significant loss in capacitance from their rated value as the DC bias voltage on the capacitorincreases. It is not uncommon for a small surface mount capacitor to lose more than 50% of its rated capacitance when operated at even half of its maximum rated voltage. This effect is generally reduced as the case size is increased for the same nominal value capacitor. As a result, it is often necessary to use a larger value capacitance or a higher voltage rated capacitor than would ordinarily be required to actually realize the intended capacitance at the operating voltage of the application. X5R and X7R dielectric types are recommended as they exhibit the best performance over the wide operating range and temperature of the LTC3129-1. To verify that the intended capacitance is achieved in the application circuit, be sure to consult the capacitor vendor's curve of capacitance versus DC bias voltage.

#### **Using the Programmable RUN Function to Operate from Extremely Weak Input Sources**

Another application of the programmable RUN pin is that it can be used to operate the converter in a hiccup mode from extremely low current sources. This allows operation from sources that can only generate microamps of output current, and would be far too weak to sustain normal steady-state operation, even with the use of the MPPC pin. Because the LTC3129-1 draws only 1.9µA typical from  $V_{IN}$  until it is enabled, the RUN pin can be programmed to keep the IC disabled until  $V_{IN}$  reaches the programmedvoltage level. Inthismanner, the input source can trickle-charge an input storage capacitor, even if it can only supply microamps of current, until  $V_{IN}$  reaches the turn-on threshold set by the RUN pin divider. The converter will then be enabled, using the stored charge in the input capacitor, until  $V_{\text{IN}}$  drops below the turn-off threshold, at which point the converter will turn off and the process will repeat.

This approach allows the converter to run from weak sources such as thin-film solar cells using indoor lighting.

Although the converter will be operating in bursts, it is enough to charge an output capacitor to power low duty cycle loads, such as wireless sensor applications, or to trickle charge a battery. In addition, note that the input voltage will be cycling (with a small ripple as set by the RUN hysteresis) about a fixed voltage, as determined by the divider. This allows the high impedance source to operate at the programmed optimal voltage for maximum power transfer.

When using high value divider resistors (in the M $\Omega$  range) to minimize current draw on  $V_{IN}$ , a small noise filter capacitor may be necessary across the lower divider resistor to prevent noise from erroneously tripping the RUN comparator. The capacitor value should be minimized so as not to introduce a time delay long enough for the input voltage to drop significantly below the desired  $V_{\text{IN}}$ threshold before the converter is turned off. Note that larger  $V_{IN}$  decoupling capacitor values will minimize this effect by providing more holdup time on  $V_{\text{IN}}$ .

#### **Programming the MPPC Voltage**

As discussed in the previous section, the LTC3129-1 includes an MPPC function to optimize performance when operating fromvoltage sourceswith relatively high source resistance. Using an external voltage divider from  $V_{IN}$ , the MPPC function takes control of the average inductor current when necessary to maintain a minimum input voltage, as programmed by the user. Referring to Figure 3:

 $V_{IN(MPPC)} = 1.175V \cdot (1 + R5/R6)$ 

This is useful for such applications as photovoltaic powered converters, since the maximum power transfer point occurs when the photovoltaic panel is operated at about 75% ofits open-circuit voltage. For example, when operating from a photovoltaic panel with an open-circuit voltage of 5V, the maximum power transfer point will be when the panel is loaded such that its output voltage is about 3.75V. Choosing values of 2MΩ for R5 and 909k for R6 will program the MPPC function to regulate the maximum input current so as to maintain  $V_{IN}$  at a minimum of 3.74V (typical). Note that if the panel can provide more power than the LTC3129-1 can draw, the input voltage will rise above the programmed MPPC point. This is fine as long as the input voltage doesn't exceed 15V.



For weak input sources with very high resistance (hundreds of Ohms or more), the LTC3129-1 may still draw more current than the source can provide, causing  $V_{IN}$  to drop below the UVLO threshold. For these applications, it is recommended that the programmable RUN feature be used, as described in the previous section.

### **MPPC Compensation and Gain**

When using MPPC, there are a number of variables that affect the gain and phase of the input voltage control loop. Primarily these are the input capacitance, the MPPC divider ratio and the  $V_{IN}$  source resistance (or current). To simplify the design of the application circuit, the MPPC control loop in the LTC3129 is designed with a relatively low gain, such that external MPPC loop compensation is generally not required when using a  $V_{IN}$  capacitor value of at least 22µF. The gain from the MPPC pin to the internal VC control voltage is about 12, so a drop of 50mV on the MPPC pin (below the 1.175V MPPC threshold), corresponds to a 600mV drop on the internal VC voltage, which reduces the average inductor current all the way to zero. Therefore, the programmed input MPPC voltage will be maintained within about 4% over the load range.

Note that if large-value  $V_{IN}$  capacitors are used (which may have a relatively high ESR) a small ceramic capacitor of at least  $4.7\mu$ F should be placed in parallel across the V<sub>IN</sub> input, near the  $V_{IN}$  pin of the IC.

### **Bootstrapping the V<sub>CC</sub> Regulator**

The high and low side gate drivers are powered through the V<sub>CC</sub> rail, which is generated from the input voltage, V<sub>IN</sub>, through an internal linear regulator. In some applications, especially at high input voltages, the power dissipation in the linear regulator can become a major contributor to thermal heating ofthe ICand overall efficiency. The Typical Performance Characteristics section provides data on the  $V_{\text{CC}}$  current and resulting power loss versus  $V_{\text{IN}}$  and  $V_{\text{OUT}}$ . A significant performance advantage can be attained in high  $V_{IN}$  applications where converter output voltage ( $V_{OUT}$ ) is programmed to 5V, if  $V_{\text{OUT}}$  is used to power the V<sub>CC</sub> rail.

Powering  $V_{CC}$  in this manner is referred to as bootstrapping. This can be done by connecting a Schottky diode (such as a BAT54) from  $V_{\text{OUT}}$  to  $V_{\text{CC}}$  as shown in Figure 5. With the bootstrap diode installed, the gate driver currents are supplied by the buck-boost converter at high efficiency rather than through the internal linear regulator. The internal linear regulator contains reverse blocking circuitry that allows  $V_{CC}$  to be driven above its nominal regulation level with only a very slight amount of reverse current. Please note that the bootstrapping supply (either  $V_{OUT}$  or a separate regulator) must be limited to less than 5.7V so as not to exceed the maximum  $V_{CC}$  voltage of 5.5V after the diode drop.

By maintaining  $V_{CC}$  above its UVLO threshold, bootstrapping, even to a 3.3V output, also allows operation down to the  $V_{IN}$  UVLO threshold of 1.8V (typical).



**Figure 5. Example of V<sub>CC</sub> Bootstrap** 

### **Sources of Small Photovoltaic Panels**

A list of companies that manufacture small solar panels (sometimes referred to as modules or solar cell arrays) suitable for usewith the LTC3129-1 is provided in Table 4.









**Low Noise, Fixed Frequency, Wide VIN Range 12V Converter**

**3.3V Converter Provides Extremely Long Run Time in Low Drain Applications Using Lithium Thionyl Chloride Battery**







**15V Converter Powered from Flexible Solar Panel**

# **IOUT vs Light Level (Daylight)** LIGHT LEVEL (Lx) IOUT (mA) 31291 TA04b 100 10 10000 10000 100000 1000000

**Hiccup Converter Keeps Li-Ion Battery Charged with Indoor Lighting** 









LINEAR

**I** 

31291 TA05b

**5V Converter Operates from Two to Eight AA or AAA Cells Using Bootstrap Diode to Increase Efficiency at High VIN and Extend Operation at Low VIN**



#### **3.3V Converter Uses MPPC Function to Work with High Resistance Battery Pack**



NOTE: R<sub>C</sub> AND C<sub>C</sub> HAVE BEEN ADDED FOR IMPROVED MPPC LOOP STABILITY WHEN USING AN INPUT<br>CAPACITOR VALUE LESS THAN THE RECOMMENDED MINIMUM OF 22µF





**Solar Powered Converter Extends Battery Life in Low Power 3V Primary Battery Applications**

#### **Percentage of Added Battery Life vs Light Level and Load (PowerFilm SP4.2-37, 30sq cm Panel)**





### Package Description

 $3.50 \pm 0.05$ 

**Please refer to http://www.linear.com/product/LTC3129-1#packaging for the most recent package drawings.**

**UD Package**



1. DRAWING CONFORMS TO JEDEC PACKAGE OUTLINE MO-220 VARIATION (WEED-4)

2. DRAWING NOT TO SCALE

3. ALL DIMENSIONS ARE IN MILLIMETERS

4. DIMENSIONS OF EXPOSED PAD ON BOTTOM OF PACKAGE DO NOT INCLUDE

MOLD FLASH. MOLD FLASH, IF PRESENT, SHALL NOT EXCEED 0.15mm ON ANY SIDE

5. EXPOSED PAD SHALL BE SOLDER PLATED

6. SHADED AREA IS ONLY A REFERENCE FOR PIN 1 LOCATION

ON THE TOP AND BOTTOM OF PACKAGE



### Package Description

**Please refer to http://www.linear.com/product/LTC3129-1#packaging for the most recent package drawings.**



**MSE Package**

3. DIMENSION DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

- MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.152mm (.006") PER SIDE
- 4. DIMENSION DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS. INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.152mm (.006") PER SIDE
- 5. LEAD COPLANARITY (BOTTOM OF LEADS AFTER FORMING) SHALL BE 0.102mm (.004") MAX

6. EXPOSED PAD DIMENSION DOES INCLUDE MOLD FLASH. MOLD FLASH ON E-PAD SHALL NOT EXCEED 0.254mm (.010") PER SIDE.



# Revision History







**TEG Powered Converter Operates from a 10°C Temperature Differential and Provides 3.3V at 25mA for 50ms Every 15 Seconds for a Wireless Sensor**



# Related Parts



31291fc LINEAR TECHNOLOGY CORPORATION 2013